

STRESS RESISTANT LAND GRID ARRAY (LGA) MODULE AND METHOD OF FORMING THE SAME

ABSTRACT OF THE DISCLOSURE

5 An integrated circuit module, a land grid array module, and a method for forming the module, include a substrate, which mounts one or more chips or discrete electronic components, and a cap for covering the substrate, and including at least one protrusion coupled to the cap for limiting the amount of flexing of the substrate during actuation. The at least one protrusion can be either rigidly fixed to the cap or adjustably inserted through the cap.